

Applicant : Schelto Van Doorn
Serial No. : 09/574,647
Filed : May 18, 2000
Page : 2 of 7

Attorney's Docket No.: 12754-064001 / 00P7629

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A transducer comprising:
a housing mountable on a substrate, the housing configured to receive a jumper cable,
an input/output (I/O) lead supported by the housing and configured to directly contact an
I/O lead of an integrated circuit, where the integrated circuit is separately mounted on the
substrate and outside of the housing of the transducer, and
electronic circuitry supported by the housing to transition between an electronic data
transfer protocol of the jumper cable and an electronic data transfer protocol of the integrated
circuit.
2. (Original) The transducer of claim 1, wherein the transducer I/O lead is configured to
electrically connect to the integrated circuit I/O lead independently of any electrically conductive
path of the substrate.
3. (Original) The transducer of claim 1, wherein the transducer I/O lead is configured to
contact the integrated circuit I/O lead at a transducer surface substantially parallel to a mounting
surface of the substrate.
4. (Original) The transducer of claim 1, wherein the transducer I/O lead is configured to
contact a pin I/O lead of the integrated circuit.
5. (Original) The transducer of claim 1, wherein the transducer I/O lead is configured to
contact a solder ball lead of the integrated circuit.

Applicant : Schelto Van Doorn
Serial No. : 09/514,647
Filed : May 18, 2000
Page : 3 of 7

Attorney's Docket No.: 12754-064001 / 00P7629

6. (Original) The transducer of claim 1, wherein the transducer I/O lead is configured to contact the integrated circuit I/O lead at a transducer surface adjacent to a mounting surface of the substrate.

7. (Original) The transducer of claim 1, further comprising a power input lead connectable to a power line of the substrate.

8. (Original) The transducer of claim 1, further comprising a transductional device.

9. (Original) The transducer of claim 1, wherein the transductional device is an opto-electronic device.

10. (Original) The transducer of claim 1, wherein the transductional device is an electronic device.

11 - 19. Cancelled.

20. (New) A transducer comprising:

a housing mountable on a substrate, the housing configured to receive a jumper cable;
an input/output (I/O) lead supported by the housing and configured to directly contact an I/O lead of an integrated circuit, where the integrated circuit is separately mounted on the substrate and outside of the housing of the transducer, and

electronic circuitry supported by the housing to transition between an electronic data transfer protocol of the jumper cable and an electronic data transfer protocol of the integrated circuit, the electronic circuitry including:

a coupler operable to couple data signals carried by a jumper cable received by the housing to a transductional device;

a transductional device operable to transition between an electronic data transfer protocol of the jumper cable and an electronic data transfer protocol of the integrated circuit; and

Applicant : Schelto Van Doorn
Serial No. : 09/574,647
Filed : May 18, 2000
Page : 4 of 7

Attorney's Docket No.: 12754-064001 / 00P7629

a circuit card operable to carry signals between the transductional device and the I/O lead supported by the housing.

21. (New) The transducer of claim 20, wherein the transducer I/O lead is configured to electrically connect to the integrated circuit I/O lead independently of any electrically conductive path of the substrate.
22. (New) The transducer of claim 20, wherein the transducer I/O lead is configured to contact the integrated circuit I/O lead at a transducer surface substantially parallel to a mounting surface of the substrate.
23. (New) The transducer of claim 20, wherein the transducer I/O lead is configured to contact a pin I/O lead of the integrated circuit.
24. (New) The transducer of claim 20, wherein the transducer I/O lead is configured to contact a solder ball lead of the integrated circuit.
25. (New) The transducer of claim 20, wherein the transducer I/O lead is configured to contact the integrated circuit I/O lead at a transducer surface adjacent to a mounting surface of the substrate.
26. (New) The transducer of claim 20, further comprising a power input lead connectable to a power line of the substrate.
27. (New) The transducer of claim 20, wherein the transductional device is an opto-electronic device.
28. (New) The transducer of claim 20, wherein the transductional device is an electronic device.